PCN# : P57UAA
Issue Date : Oct. 06, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product :Jan. 04, 2016

Expected First Date Code of Changed Product :1602

Description of Change (From) :
Front-end Wafer Fabrication site Fairchild Bucheon 5-in wafers
Existing assembly/test source located at Weihai China, Shantou China, Suzhou,China

Description of Change (To) :
Front-end Wafer Fabrication Site Hangzhou Silan Foundry 5-inch wafers for HP BJT
Adding Back-end assembly/test source located at Shanwei China

Reason for Change:
Improve supply flexibility.
Better quality and yields through equipment and facility upgrades.
- Increased automation in handling and inspection in assembly.
Fairchild partners with foundries and assembly subcontractors.
- Best manufacturing practices, access to many customers methods and practices.
- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your companys procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	FJL6920TU	TO264	HP BJT	3

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	11/13/2015
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	12/18/2015
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	12/18/2015
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	12/18/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	9/28/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	TIP42CTU_F129	TO220	HP BJT	3

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	0/231
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	9/21/2015
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	9/21/2015
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	9/22/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	BD13916STU	TO126	HP BJT	2

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	9/25/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/154

Qualification Plan	Device	Package	Process	No. of Lots
Q20150269	FJP2160DTU	TO220	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	0/154
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	10/5/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150269	FJD3305H1TM	TT252	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/77
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	9/25/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	10/13/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20140407	KA7805AETU	TO220	BHB2A	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=20V	JESD22-A101B	1000 hrs	0/77
High Temperature Op Life	125C,Vin=30V	NA	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140407	KSA940TU	TO220	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Medium Size Pkg's (TO-220, D2) (Power Cycle)	Delta 100C, 3.5 Min On/Off	MIL-STD-750 M1037	8572 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140407	FCP36N60N	TO220	SUPREMOS	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Gate Bias	150C, 100% Rated VGSV	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Medium Size Pkg's (TO-220, D2) (Power Cycle)	Delta 100C, 3.5 Min On/Off	MIL-STD-750 M1037	8572 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140407	TIP42CTU	TO220	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Medium Size Pkg's (TO-220, D2) (Power Cycle)	Delta 100C, 3.5 Min On/Off	MIL-STD-750 M1037	8572 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140407	FQP4N90C	TO220	C-FET	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Gate Bias	150C, 100% Rated VGSV	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Medium Size Pkg's (TO-220, D2) (Power Cycle)	Delta 100C, 3.5 Min On/Off	MIL-STD-750 M1037	8572 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140409A	FQD17N08LTM	DIPAK	Q-FET	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL(1), PKG(Small), (Precondition),Before TMCL/H3TRB test	PeakTemp(260c), Cycles(3)	JESD22-A113	24 hrs 168hrs	0/154
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140409A	MJD47TF	DIPAK	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL(1), PKG(Small), (Precondition),Before TMCL/H3TRB test	PeakTemp(260c), Cycles(3)	JESD22-A113	24 hrs 168hrs	0/154
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C,	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140409A	LM317MDTX	DIPAK	BSP1	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL(1), PKG(Small), (Precondition),Before TMCL/THBT test	PeakTemp(260c), Cycles(3)	JESD22-A113	24 hrs 168hrs	0/154
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=13V	JESD22-A101B	1000 hrs	0/77
High Temperature Op Life	Vin=19V Ta=125C	NA	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Solder Dip (Resistance to Solder Heat)	270C,	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140409A	FQU13N10LTU	DIPAK	Q-FET	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Humidity, High Temp, Rev. Bias	85C, 85%RH, Vin=80% of rated BV, max 100V	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias	150C, 80% ratedBV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Solder Dip = 260C, 10 sec (Resistance to Solder Heat)	270C,	JESD22-B106	15 sec	0/30
-65C, 150C (Temperature Cycle)	-65C, 150C	JESD22-A104	500 cyc	0/77